



I'm not robot



I'm not robot!

This document describes specific guidelines for strain gage testing for printed wiring board (pwb) assemblies in the board manufacturing process including, assembly, test, system integration and board shipping. intel board flexure guidance aligns to ipc- 9704 and ipc- 9707 standards. ipc jedec- pdf 9704a - printed circuit assembly strain gage test guideline strain gage testing allows for objective analysis of the strain and strain rate levels to which a surface mount package may be subjected to during assembly, test and operation. at least 3 channels (12 or more recommended) simultaneous sampling of all channels. download a full copy of the ipc/ jedec- 9704 guideline from the jedec web site. ipc/ jedec 9704a- cn- printed circuit assembly board strain gage test guidelines (chinese version) describes specific guidelines for strain gage testing during the printed pdf board manufacturing process, including board assembly, test, system integration and other types of operations that may induce board flexure. download a full copy of the ipc/ jedec- 9704 guideline from the ipc web site. this document has been replaced.

the document is meant to be used in conjunction with the strain gage procedure described in ipc/ jedec 9704. in the following sections of this white paper, learn about the four pcb strain gage testing steps as recommended by the ipc- 9704 guideline. 12 to 16 bit input resolution. sampling rate of 2khz. low - pass filter. excessive strain can result in various failure modes for different solder alloys, package types, surface finishes or laminate materials. metric: in the applicable assembly steps, diagonal strain guidance should be compared to the maximum calculated diagonal strain (other metrics, such as principal strain should pdf not be used). the suggested procedures enables board manufacturers to conduct ipc 9704 pdf required strain gage testing independently, and provides a quantitative method for measuring board flexure, and assessing risk levels. printed circuit assembly strain gage test guideline. view the most recent version. sgt system i/ o requirements.

discrete surface mount technology (smt) devices, (e. this document is meant to be used as a methodology for strain gage placement and subsequent testing of printed circuit assemblies (pcas) using strain gages. the method describes specific guidelines. this document gathers and organizes common standards and publications relating to quality processes and methods relating to the solid-state, microelectronics, and associated industries.

when an ipc publication is updated and a new revision is published, it is the opinion of the taec. strain gage testing allows for objective analysis of the strain and strain rate levels to which a surface mount package may be subjected to during assembly, test and operation. this guidance assumes a surface mount device; ball grid array (bga), small outline package (sop) and chip scale (size) package (csp) are typical device examples. it is ipc 9704 pdf the position of ipc s technical activities executive committee that the use and implementation of ipc publications is voluntary and is part of a relationship entered into by customer and supplier.

using ipc/ jedec- 9704 & 9702 standards for strain gage testing of your printed wiring boards swapnil padhye national instruments. location: accurate strain gage rosette positioning is required to compare. consultant, who ipc hub 2: 28 pm innovative ipc education and training stories: presentations of top 3 stories submitted to who tba 2: 46 pm introducing the global ipc in- service curriculum: an overview mandy deeves, technical officer, who ipc hub 2: 56 pm my 5 moments: the game" - revolutionizing hand hygiene education ermira tartari,. document history. ipc jedec- 9704a – printed circuit assembly strain

gage test guideline. this is intended to facilitate access to the applicable documents when working with electronic hardware.

standard by association connecting electronics industries,. ipc/ jedecprinted wiring board strain gage test guideline. excessive strain can result in various failure modes for different solder alloys, package types. printed wiring board strain gage test guideline. ipc jedec- 9704a printed circuit assembly strain gage test guideline. full description. ipc/ jedec- 9704. this document describes specific guidelines for strain gage testing for printed wiring board (pwb) assemblies. view all product details.